Indian Representative
Bergen Systems Pvt. Ltd.
Gurgaon
www.bergenindia.com

Bergen Systems

VISCOM
vision technology

Company Profile

Viscom inspection systems are used in virtually every branch of industry – from automotive electronics to aerospace technology, to industrial electronics and the semiconductor and photovoltaic industries. Steadily rising requirements for quality and increasing mechanization in all areas of life require 100 % quality assurance using intelligent, automatic inspection solutions.

Material weaknesses or production defects have economic disadvantages for the manufacturer and potentially fatal consequences for the end user. This is why well-known companies all around the world place their trust in Viscom.

Highly qualified engineers develop application-oriented inspection solutions in close cooperation with our customers. Furthermore, we stand by our customers with advice and support – regardless of whether technical details, questions on system integration, application or comprehensive process optimization are concerned.

Viscom – Your Partner
for all Inspection Tasks

Satisfied customers are our most important corporate goal

Constant innovation through close customer contact and continuous research and development

High manufacturing penetration guarantees flexibility

In-house design and tool making

Internal hardware and software development

Highly qualified team of engineers

Highly motivated employees who believe in Viscom's mission and purpose

First-class service and support worldwide

Close working relationship between employees and costumers

Viscom AG
Carl-Buderus-Str. 9-15
30455 Hanover, Germany
Www.viscom.com

Example uses of successful inspection solutions

Technology

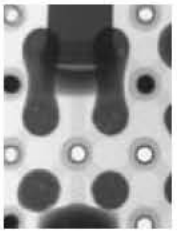
Defect detection

With the automatic optical batch inspection systems, all inspection gates in the electronics production (i. e. paste print, assembly and solder joint) are covered. 8M camera technology, inclined inspection, OnDemandHR and color evaluation – those are the keywords that indicate the performance advantage of Viscom. This guarantees the greatest inspection depth and the reliable detection of critical defects.

Modern components, which don't show a visible solder joint, such as µBGA or QFN's can easily be inspected with Viscom AXI systems or combination systems that combine optical inspection and X-ray inspection.

Paste

Assembly



Solder joint

Viscom's product line ranges from microfocus X-ray tubes, OEM products and off-line inspection islands to fully automated systems with a µCT option. The high-performance microfocus X-ray tubes produced in-house at Viscom enable non-destructive testing of a broad range of different objects and materials. The applications range from PCBs and electronic components to tasks of the non-destructive testing (NDT), e. g. from light bulbs, cast parts etc.

Microfocus computed tomography supplies insights into internal structures. Using slice images, 3-D images are created which, for example, are used for prototype qualification and reverse engineering or in process tests.

Light bulb (µCT)

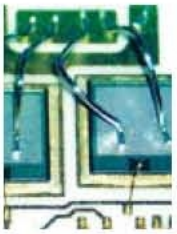
Crimped connection (µCT)

Turbine rotor 2-D X-ray image

With intelligent inspection cells for versatile applications, Viscom offers customized solutions in the NP sector, e. g. for the electronics industry, medical industry and for mechanical engineering. For example, Viscom develops complete customer-specific solutions for measuring and characterization tasks, for assembly inspection or special solder joint inspections. In addition, Viscom also offers AOI systems for inspection of solar cells, thick-film and bare board inspection. Viscom is the world leader in wire-bond inspection.

Chipping

Wire defect (Curling)



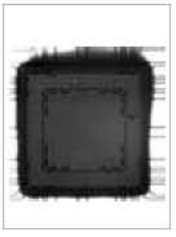
Drilled hole inspection

The IP business segment specializes in the inspection of wafers for semiconductor production. The heart of the inspection systems is the unique infrared technology. It enables irradiation of the silicon, which permits the detection of defects both on and below the wafer surface.

The focus of the IP product line is the quality control of bonded wafers and MEMS. Other applications include the inspection of FlipChip components and the photovoltaic sector.

Missing Seal

FlipChip underfilling



Wafer defect

Viscom Automatic Inspection Systems

- Highest Inspection depth with 8 module Cameras
- Selective high resolution with OnDemandHR Operation
- Precise Linear Drive
- High Resolution Colour evaluation
- Suitable for Standard & Lead Free electronic assemblies
- Fast program creation with EasyPro3D
- Algorithm based inspection

Viscom Desktop Automatic Inspection System S2088

- **Sharp Inspection Depth down to 0201, 0.4 mm raster**
- **Compact system with integrated PC**
- **Precise Linear Drive**
- **High Resolution Colour Camera**
- **High Performance OCR Software**
- **Worldwide Competent Services with remote diagnosis options**
- **Rapid Programming with EasyPro**